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Global SiC Wafer Thinning Equipment Supply, Demand and Key Producers, 2026-2032

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Abstracts

The global SiC Wafer Thinning Equipment market size is expected to reach $ 219 million by 2032, rising at a market growth of 8.6% CAGR during the forecast period (2026-2032).

Wafer Grinder uses a centrally located robot to move a wafer from an input station to a measuring station. Thereafter, the wafer is moved into a grind station and a wash station sequentially. The robot is able to move a wafer from the wash station to either the measuring station for after-grinding measurements or directly to an output station. During grinding of one wafer, a second wafer may be held between the measuring station and the grind station while a ground wafer is moved from the wash station to the measuring station for after-grinding measurements.

This report only studies Silicon Carbide Wafer Thinning Equipment.

In 2025, global SiC Wafer Thinning Equipment production reached approximately 254 units, with an average global market price of around US$ 513 k per unit.

The upstream inputs for SiC wafer thinning equipment consist primarily of functional components and structural materials. Critical components include control systems, motion controllers, power electronics and precision sensors, while structural materials mainly comprise steel and enclosure materials used in machine frames and housings. Core suppliers in these categories include Siemens and Rockwell Automation for automation and control hardware, as well as Shagang Group and BASF for metallic and chemical raw materials used in machine construction and processing subsystems.

SiC wafer thinning equipment is deployed across production lines for both 6-inch-and-

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below and 8-inch-and-above wafer formats, reflecting the industry's transition toward larger substrates in power semiconductor manufacturing. Typical end users include leading global SiC wafer and device manufacturers such as Wolfspeed and Coherent, etc.

Because SiC wafer thinning equipment involves high mechanical rigidity, advanced motion control, proprietary process know-how and strong customer customization, the segment typically commands relatively high profitability. Industry-wide gross margins are generally in the range of 45–60%.

The global market for SiC Wafer Thinning Equipment is expanding rapidly as silicon carbide becomes the substrate of choice for next-generation power semiconductors used in electric vehicles, renewable energy systems and industrial power electronics. From a product-type perspective, the market is clearly dominated by fully-automatic systems, which integrate robotic wafer handling, inline metrology, grinding and cleaning modules and factory automation interfaces in order to meet the strict productivity and yield requirements of high-volume fabs. Fully-automatic tools are expected to account for approximately 78% of global market revenue in 2025, reflecting customers' preference for higher throughput, lower labor dependence and tighter process control, while semi-automatic systems continue to serve pilot lines and small-batch production environments but represent a smaller and gradually declining portion of overall demand.

From the application standpoint, SiC wafer thinning equipment is deployed across both 6-inch-and-below and 8-inch-and-above wafer formats, mirroring the industry's transition toward larger substrates. Nevertheless, 6-inch-and-below lines remain the dominant application segment, representing about 69% of global market demand in 2025, as the majority of current SiC device capacity is still concentrated in legacy 150-millimeter platforms and their associated back-end process flows. At the same time, investments in 8-inch fabs are accelerating and are expected to reshape the demand mix over the medium term, creating new opportunities for advanced thinning systems capable of handling larger, thinner and more fragile wafers with high yield.

Market growth is being driven by the rapid penetration of electric vehicles, charging infrastructure and renewable-energy inverters, all of which rely heavily on SiC power devices to achieve higher efficiency and power density. Continued government support for energy transition and domestic semiconductor supply chains, together with rising capital expenditure by integrated device manufacturers and wafer suppliers, is stimulating sustained equipment purchases. Technological trends such as thinner substrates for advanced packaging, higher power module integration and tighter thermal-

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management requirements are further increasing the performance specifications for thinning tools, favoring suppliers able to deliver highly automated and process-optimized platforms.

Despite these favorable dynamics, the market also faces several restraining factors. The capital-intensive nature of SiC fabs makes equipment spending sensitive to cyclical downturns in the automotive and industrial sectors, potentially leading to temporary order delays. Long qualification cycles and strict reliability standards imposed by power-electronics customers can slow the adoption of new equipment platforms, while intensified competition among tool vendors may exert pricing pressure in certain regions. In addition, the technical challenges associated with grinding extremely hard SiC substrates to ultra-thin thicknesses without inducing subsurface damage continue to require heavy investment in research and service capabilities, raising operating costs and limiting rapid capacity expansion for some suppliers.

This report studies the global SiC Wafer Thinning Equipment production, demand, key manufacturers, and key regions.

This report is a detailed and comprehensive analysis of the world market for SiC Wafer Thinning Equipment and provides market size (US$ million) and Year-over-Year (YoY) Growth, considering 2025 as the base year. This report explores demand trends and competition, as well as details the characteristics of SiC Wafer Thinning Equipment that contribute to its increasing demand across many markets.

Highlights and key features of the study
Global SiC Wafer Thinning Equipment total production and demand, 2021-2032, (Units)
Global SiC Wafer Thinning Equipment total production value, 2021-2032, (USD Million)
Global SiC Wafer Thinning Equipment production by region & country, production, value, CAGR, 2021-2032, (USD Million) & (Units), (based on production site)
Global SiC Wafer Thinning Equipment consumption by region & country, CAGR, 2021-2032 & (Units)
U.S. VS China: SiC Wafer Thinning Equipment domestic production, consumption, key domestic manufacturers and share
Global SiC Wafer Thinning Equipment production by manufacturer, production, price, value and market share 2021-2026, (USD Million) & (Units)
Global SiC Wafer Thinning Equipment production by Type, production, value, CAGR, 2021-2032, (USD Million) & (Units)
Global SiC Wafer Thinning Equipment production by Application, production, value, CAGR, 2021-2032, (USD Million) & (Units)

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This report profiles key players in the global SiC Wafer Thinning Equipment market based on the following parameters - company overview, production, value, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include Disco, TSD, TOKYO SEIMITSU, Engis Corporation, Okamoto Semiconductor Equipment Division, Revasum, Koyo Machinery, G&N, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Stakeholders would have ease in decision-making through various strategy matrices used in analyzing the World SiC Wafer Thinning Equipment market

Detailed Segmentation:

Each section contains quantitative market data including market by value (US$ Millions), volume (production, consumption) & (Units) and average price (K US$/Unit) by manufacturer, by Type, and by Application. Data is given for the years 2021-2032 by year with 2025 as the base year, 2026 as the estimate year, and 2027-2032 as the forecast year.

Global SiC Wafer Thinning Equipment Market, By Region:

United States

China

Europe

Japan

South Korea

ASEAN

India

Rest of World

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Global SiC Wafer Thinning Equipment Market, Segmentation by Type:

Full-Automatic

Semi-Automatic

Global SiC Wafer Thinning Equipment Market, Segmentation by Number of Spindles:

Single Spindle

Dual Spindle

Global SiC Wafer Thinning Equipment Market, Segmentation by Number of Workstations:

Single-Station

Multi-Station

Global SiC Wafer Thinning Equipment Market, Segmentation by Application:

6 Inch and Below

8 Inch and Above

Companies Profiled:

Disco

TSD

TOKYO SEIMITSU

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Engis Corporation

Okamoto Semiconductor Equipment Division

Revasum

Koyo Machinery

G&N

Key Questions Answered:

1. How big is the global SiC Wafer Thinning Equipment market?
2. What is the demand of the global SiC Wafer Thinning Equipment market?
3. What is the year over year growth of the global SiC Wafer Thinning Equipment market?
4. What is the production and production value of the global SiC Wafer Thinning Equipment market?
5. Who are the key producers in the global SiC Wafer Thinning Equipment market?
6. What are the growth factors driving the market demand?

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